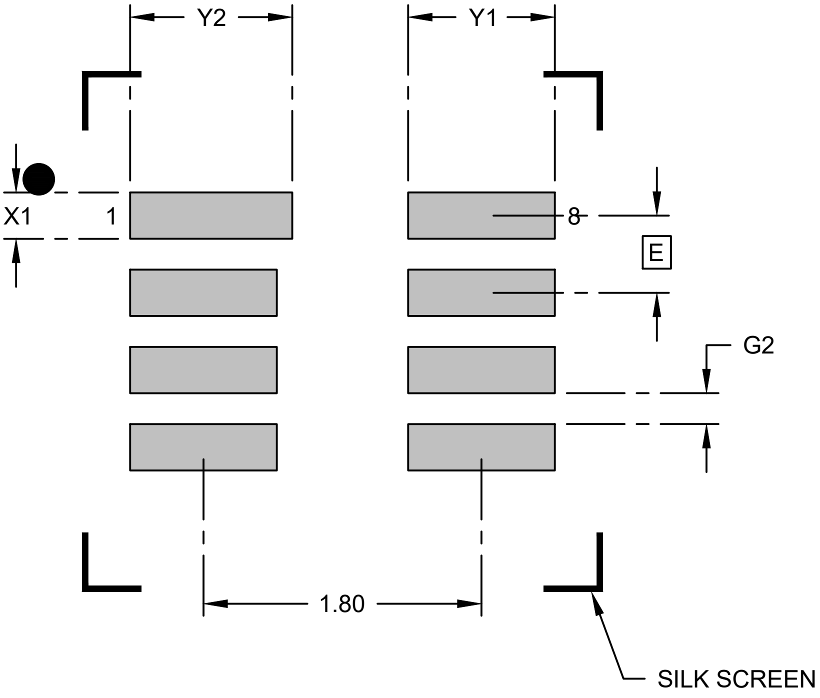
8-Lead Thin Dual Flatpack No-Lead (8HW) 2x2x0.8mm Body [TDFN] With Chip On Lead

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
		Dimension Limits	MIN	NOM	MAX
Contact Pitch	E		0.50 BSC		
Contact Pad Spacing	C			1.80	
Contact Pad Width (X8)	X1				0.30
Contact Pad Length (X7)	Y1				0.95
Pin 1 Contact Pad Length (X1)	Y2				1.05
Contact Pad to Contact Pad (X6)	G2		0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. The theoretically exact value is shown without tolerances.
2. For best soldering results, please refer to the current industry standard IPC-7093.